#### Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

Except below description page
 "Request for your special attention and precautions in using the technical information and semiconductors described in this book"

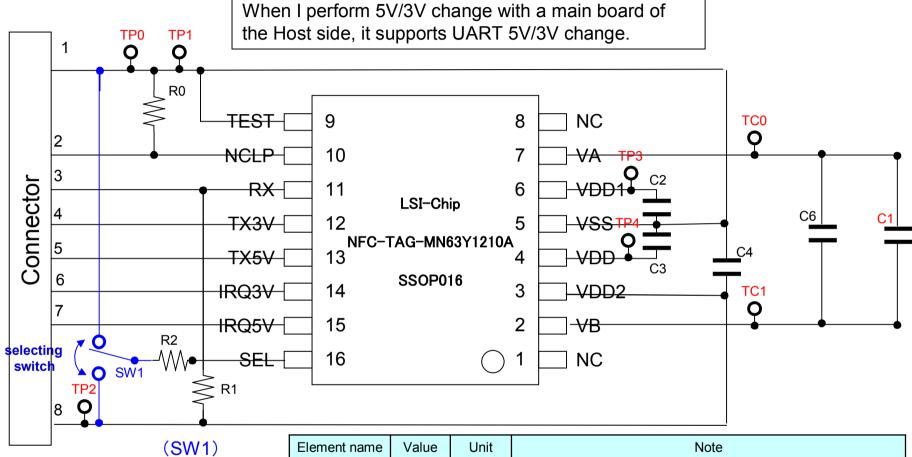
Nuvoton Technology Corporation Japan

# Evaluation board circuit diagram and implementation < MN63Y1210A >

Ver 1.1

2013/10/21

Automotive & Industrial Systems Company Panasonic Corporation

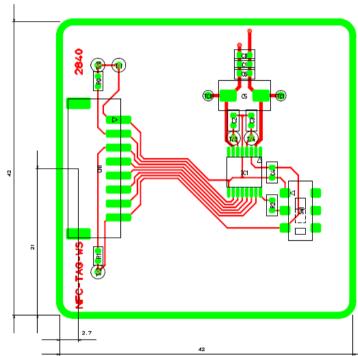


	(OVVI)
S8B-PH-SM4-TB	CL-SB-22B-01

Element name	Value	Unit	Note
C1	27	pF	Condenser implementation for resonance frequency adjustment
C2	0.1	mF	
C3	0.01	mF	
C4	0.1	mF	
C6	330	pF	Condenser implementation for resonance frequency adjustment
R0、R1	100	kΩ	It is for reference board alone evaluations
R2	0	Ω	

## Pattern drawing and part list of Evaluation board

#### Pattern drawing



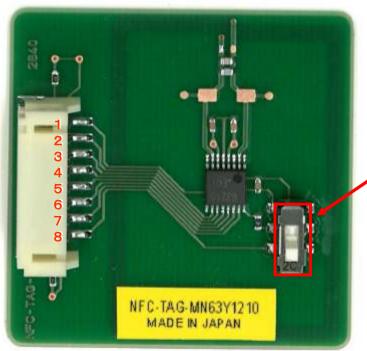
#### Parts list

		No	Part Number	Manufacturer	Parameter	Tolerance	Rated V/ W	LxW [mm]
	IC1		NFC-TAG-MN63Y1210A	Panasonic	_	_	4.6V	6.4×5
	CN1 TP0		S8B-PH-SM4-TB	JST	_	_	100V	19.9x8.6
			Unconnected Pin	_	_	_	_	-
		TP1	Unconnected Pin	_	_	_	_	_
		TP2	Unconnected Pin	ı	1	1	-	-
	TP3 TP4 R0 R1		Unconnected Pin	_	_	_	_	-
			Unconnected Pin	_	_	_	_	-
			RK73B1JTTD104J	KOA	100kΩ	±5%	0.1W	1.6x0.8
			RK73B1JTTD104J	KOA	100kΩ	±5%	0.1W	1.6x0.8
	R	UART	RK73Z1JTTD	KOA	0∼50mΩ	-	0.1W	1.6x0.8
	2	CLK synchronous	Unconnected Pin	_	_	_	-	_
	R UART		Unconnected Pin	_	_	_	_	-
	3	CLK synchronous	RK73Z1JTTD	KOA	0~50mΩ	_	0.1W	1.6x0.8
	CO		_	_	_	_	-	-
Ŧ	C1		_	_	_	_	_	-
	C2		GRM188R71E104KA01D	Murata	0.1 μ F	±10%	25V	1.6×0.8
	C3 C4 C6		GRM188R71H103KA01D	Murata	0.01 μ F	±10%	25V	1.6×0.8
			GRM188R71E104KA01D	Murata	0.1 μ F	±10%	25V	1.6×0.8
			GRM1885C1H331JA01D	Murata	330pF	±5%	50V	1.6x0.8

The change with the expression, please reach with a switch in UART and the CLK same period.

After having changed it, please carry out an initialization of the smartphone side.

Pin Number	Terminal Name
1	VSS
2	NCLP
3	RX
4	TX3V
5	TX5V
6	IRQ3V
7	IRQ5V
8	VDD2
	·



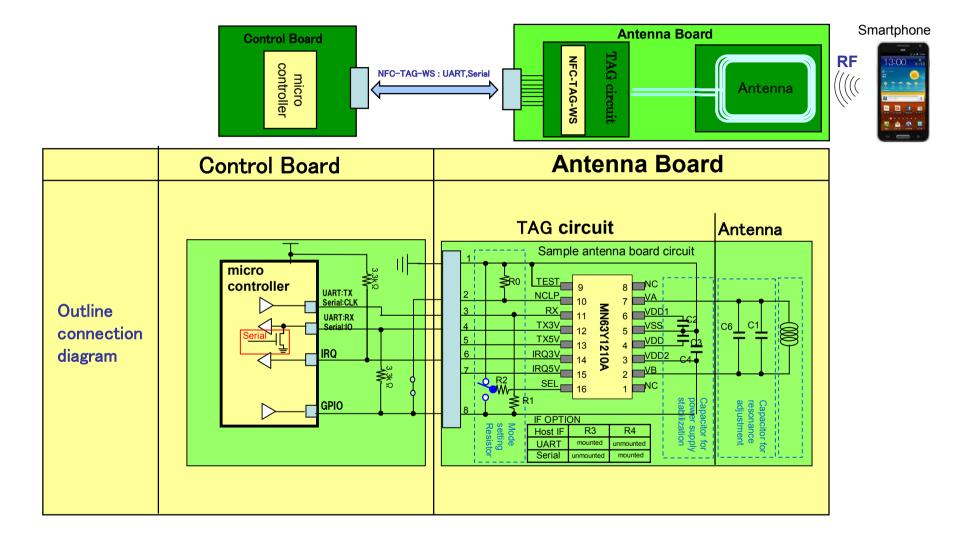
#### selector switch

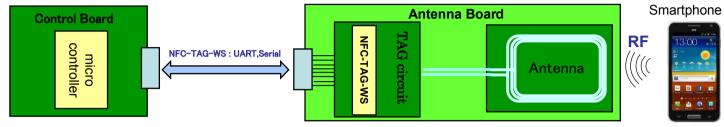
Upper: UART

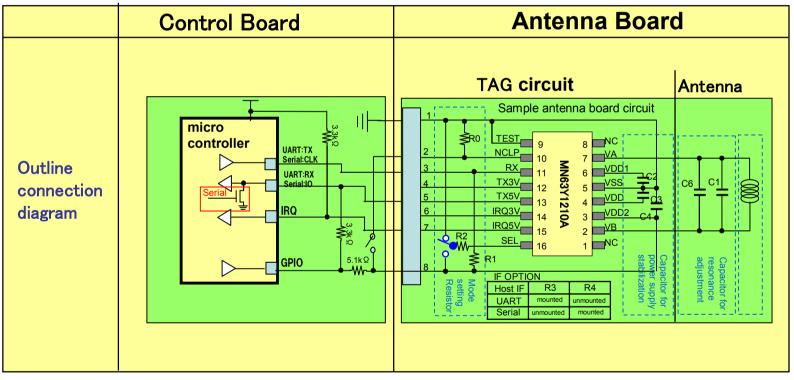
Under : CLK synchronization type

(Default)

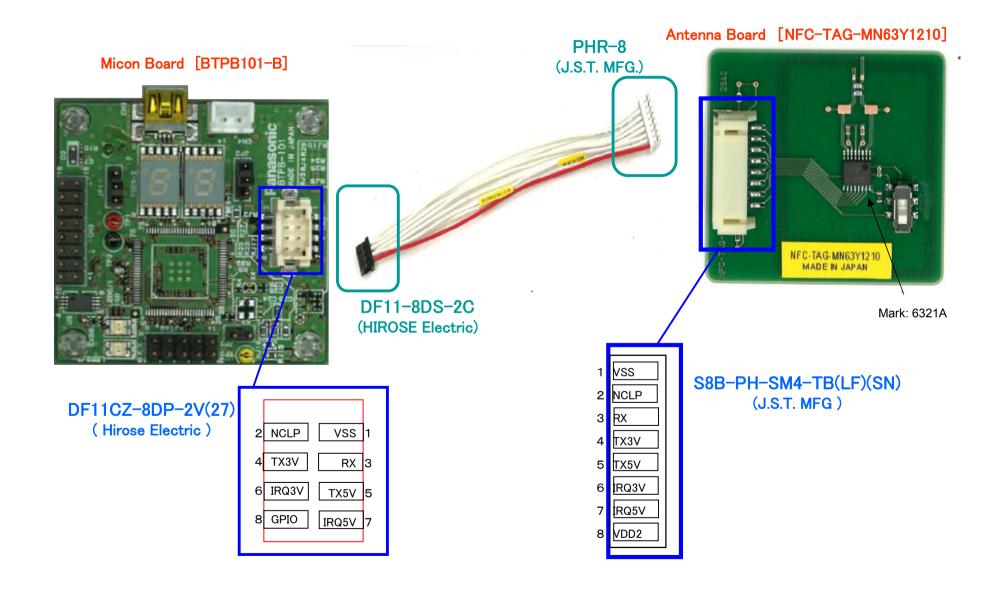
### Connection example with MCU board for 3.3V







## Connector specifications



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